



SONNENSCHN, NATH & ROSENTHAL

8000 Sears Tower
233 S. Wacker Drive
Chicago, IL 60606
312/876-8000

IN RE APPLICATION OF: Yuji Takaoka, et al.

ATTORNEY DOCKET NO. 09792909-4794

SERIAL NO.: 09/816,055

GROUP ART UNIT: 2813

FILED: March 23, 2001

EXAMINER: N. Berezny

FOR: "SEMICONDUCTOR DEVICE HAVING A PLURALITY OF ENCRUSTED SEMICONDUCTOR CHIPS (AS AMENDED)"

AMENDMENT "B"

Hon. Assistant Commissioner of Patents
Washington D.C. 2023
SIR:

Transmitted herewith is an amendment in the above-identified application.

■ No additional claim fee is required.

The fee has been calculated as shown below.

CLAIMS AS AMENDED						
	(2) CLAIMS REMAINING AFTER AMENDMENT		(4) HIGHEST NO. PREVIOUSLY PAID FOR	(5) PRESENT EXTRA	(6) RATE	(7) ADDITIONAL FEE
TOTAL CLAIMS		MINUS	20		() X 9.00 () X 18.00	0.00
INDEP. CLAIMS		MINUS	3		() X 39.00 () X 80.00	0.00
Application amended to contain any multiple dependent claims not previously paid for.				() YES () NO	() \$130.00 () \$260.00 ONE TIME	
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00	

* If the entry in Column 2 is less than the entry in Column 4, write "0" in Column 5

** If the "Highest Number Previously Paid For" IN THIS SPACE is less than 20 write "20" in this space.

- ☐ Applicant petitions the Commissioner of Patents and Trademarks to extend this time for response to the Final Office Action dated ___ for ___ month(s) so that the period for response is extended to ___. A check in the amount of \$ _ to cover the required fee is enclosed.
- ☐ A check in the amount of \$ _ to cover the additional claim fee is enclosed.
- ☐ A check for \$ _ accompanying attached Terminal Disclaimer under 37 C.F.R. §1.321.
- ☐ A check for \$ _ and Petition
- The Commissioner is hereby authorized to any additional fees which may be required, or to credit any overpayment to account No. 19-3140. A duplicate of this sheet is enclosed.
- When phoning re this application, please call 312/876-8000 - Ext. 2606.

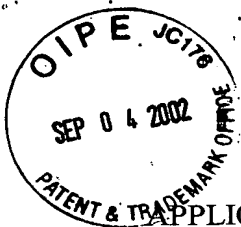
SONNENSCHN NATH & ROSENTHAL

BY Christopher P. Rauch (Reg. No. 45,034)
Christopher P. Rauch

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to the Assistant Commissioner of Patents, Washington, D.C. 20231 on August 30, 2002

Christopher P. Rauch
SIGNATURE
August 30, 2002



#10/A
Amdt.
J. McNeillan
9/12/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

AMENDMENT "B"

APPLICANTS: Yuji Takaoka et al. ATTY DOCKET NO: 09792909-4794
SERIAL NO.: 09/816,055 GROUP ART UNIT: 2813
DATE FILED: March 23, 2001 EXAMINER: Nema Berezny
INVENTION: "SEMICONDUCTOR DEVICE HAVING A PLURALITY OF
ENCUSTED SEMICONDUCTOR CHIPS (As Amended)"

Hon. Assistant Commissioner for Patents
Washington, DC 20231

S I R:

This Amendment "B" is filed in response to the Office Action of July 12, 2002.
reconsider the application in view of the amendment and remarks presented below.

IN THE DRAWINGS

Please amend Figures 7A and 7B as indicated on the drawing sheets highlighted in red
submitted with the Request for Approval of Drawing Changes submitted herewith.

IN THE TITLE OF THE INVENTION

Please replace the Title of the Invention with the following replacement Title of the
Invention:

--SEMICONDUCTOR DEVICE HAVING A PLURALITY OF ENCRUSTED
SEMICONDUCTOR CHIPS--

IN THE ABSTRACT OF THE DISCLOSURE

Please replace the Abstract of the Disclosure with the following replacement Abstract of
the Disclosure:

--A semiconductor device of MCM type allowing high-density assembly and a process
of fabricating the same is provided. There are provided semiconductor chips mounted on a
supporting substrate and incrustated in an insulation film on the supporting substrate and wiring
formed in the insulation film so as to connect to each semiconductor chip through connection
holes provided in the insulation film. Then, an interlayer dielectric covers such wiring that is
connected to an upper layer wiring, through connection holes provided in such interlayer
dielectric. In addition, an upper layer insulation film covers the upper layer wiring, and an
electrode, connected to such upper layer wiring through another connection hole, is provided on
such upper layer insulation film.--